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NGTD8R65F2

Fast Switching Rectifier Die

Fast switching low Vf rectifier die for free-wheeling applications.

Features

- Fast Switching
- Low Vf

Typical Applications

- Industrial Motor Control
- Solar PV Inverters

MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V _{RRM}	650	V
Max Forward Conduction Current	۱ _F	(Note 1)	А
Maximum Junction Temperature	ТJ	175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Depending on thermal properties of assembly.

MECHANICAL DATA

Parameter	Value	Unit	
Die Size	2817 x 2817	μm²	
Die Thickness	10	mils	
Wafer Size	150	mm	
Top Pad Size (Anode)	2376 x 2376	μm²	
Top Metal (Anode)	4 μm AlSi		
Back Metal (Cathode)	2 μm TiNiAg		
Max possible chips per wafer	1623		
Passivation frontside	Oxide-Nitride		
Reject ink dot size	25 mils		
Recommended storage environment: In original container, in dry nitrogen, or temperature of 18–28°C, 30–65%RH	Type: Bare Wafer in Jar Storage time: < 36 months	Type: Die on tape in ring-pack Storage time: < 3 months	

ORDERING INFORMATION

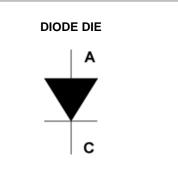
Device	Inking?	Shipping
NGTD8R65F2WP	Yes	Bare Wafer in Jar
NGTD8R65F2SWK	Yes	Sawn Wafer on Tape



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 $V_{RRM} = 650 V$ I_F = Limited by T_{J(max)}



2817 µm CC14 E 180 µm 2376 µm

DIE OUTLINE

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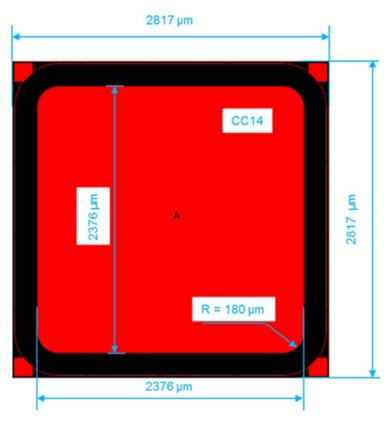
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ELECTRICAL CHARACTERISTICS (T_J = 25° C, unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Units	
STATIC CHARACTERISTICS							
Forward Voltage	I _F = 30 A, T _J = 25°C	V _F		2.1	2.8	V	
Reverse Voltage	$I_R = 320 \ \mu A, \ T_J = 25^{\circ}C$	V _R	650			V	
Reverse Current	$V_{R} = 650 \text{ V}, \text{ T}_{J} = 25^{\circ}\text{C}$	I _R	-1.0		1.0	μA	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

DIE LAYOUT



A = Anode pad All dimensions in μm

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Further Electrical Characteristic

Switching characteristics and thermal properties are depending strongly on module design and mounting technology and can therefore not be specified for a bare die.

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